

PRODUCT NUMBER
10056845-YXXYLF

CODE

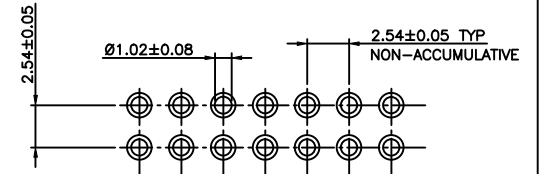
- 1 - SOLDER TAIL : 2.00mm
2 - SOLDER TAIL : 3.05mm
S - SPECIFIC CUSTOMER PLATING OPTION
WITH SOLDER TAIL : 2.00mm

STYLE	SIZE
06	2x03
08	2x04
10	2x05
14	2x07
16	2x08
20	2x10
26	2x13
30	2x15
34	2x17
40	2x20

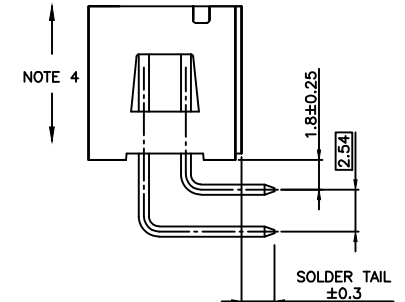
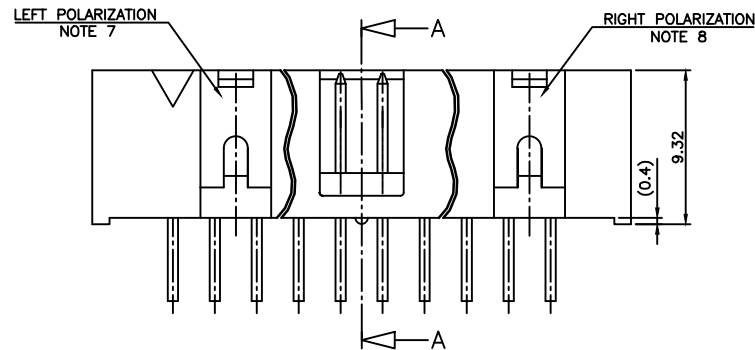
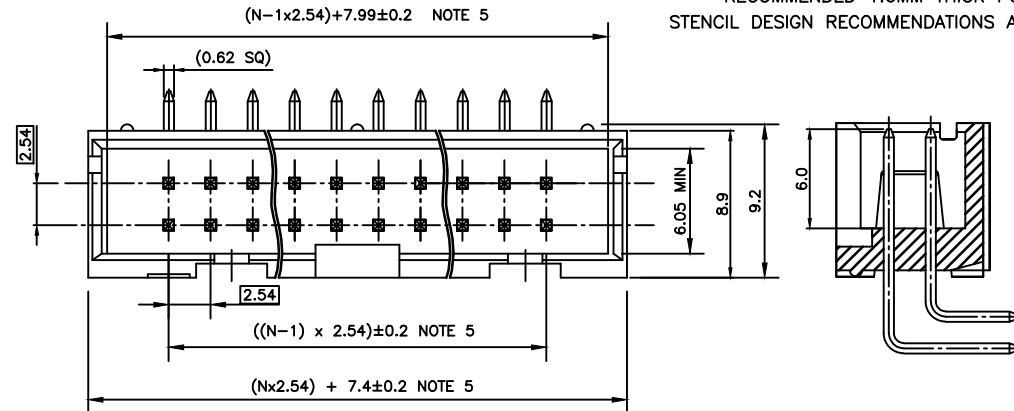
LEAD FREE, RoHS COMPATIBLE, NOTE 9.
PACKAGING NOTE 6

NOTES:

- HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, UL94 V-0 COLOR BLACK.
- CONTACT MATERIAL: COPPER ALLOY
- PLATING SPECIFICATIONS :
0.76µm GOLD/GXT
(PdNi WITH GOLD FLASH)
ON CONTACT AREA
2µm MIN MATTE TIN ON TAILS.
1.27µm NICKEL MIN UNDERPLATING
- MINIMUM PUSH OUT FORCE OF PIN IN EITHER DIRECTION : 20N BEFORE SOLDERING.
- TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS N x 2.54 = 20.32mm
- PACKAGING:
OMMIT = STANDARD TUBE PACKAGING.
K = TAPE AND REEL PACKAGING WITHOUT CAP ON REQUEST.
- NO LEFT POLARIZATION ON STYLE 06, 08, 10, 14.
- NO RIGHT POLARIZATION ON STYLE 06, 08.
- RoHS COMPLIANT & COMPATIBLE PRODUCT SPECIFICATIONS
 - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE AND RoHS COMPLIANT
2µm MINIMUM MATTE TIN ON TAILS OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
 - THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS PER GS-47-0004.
 - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10-30 SECONDS IN A CONVECTION INFRA-RED OR VAPOR PHASE REFLOW OVEN.



RECOMMENDED 1.6MM THICK PCB LAYOUT,
STENCIL DESIGN RECOMMENDATIONS AS PER TA-894



mat'l. code	surface	tolerance	projection	product family
NOTES 1, 2	ISO 1302 ✓	ISO 406 ISO 1101		QKIE HDR
ltr	ecn no	dr	date	title
H	B-19070	LMU	14.10.15	QKIE HEADER
				LOW PROFILE PIN IN PASTE
C	F07-0198	LMU	07.05.30	dwg no
D	F08-0148	YOV	08.04.11	sheet 1 of 1
E	F12-0089	JCO	12.07.23	size
F	B-18016	JCO	14.06.19	10056845
G	B-18066	LMU	14.06.24	A3
				type
				CUSTOMER
				Drawing
sheet	revision			
index	sheet			